

SUA-110E5-30xx-S277

鍍層厚度：

HOUSING：

Blank : 1u"
2 : 15u"
3 : 30u"

Blank : LCP,Blue
K : LCP,BLack
GR : PBT,Green

NOTE:

1.MATERIAL:

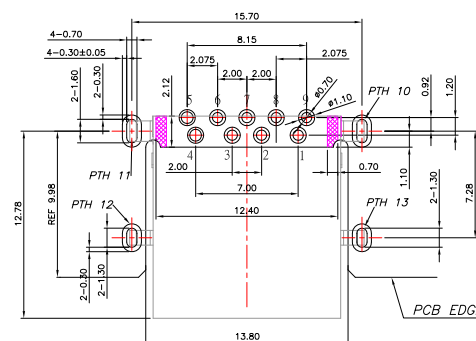
- 1.1 Housing: Plastic,(UL94V-0)
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

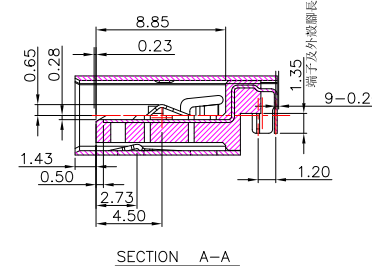
- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

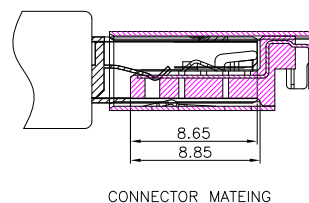
- 3.1 Rate: 30V DC , 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



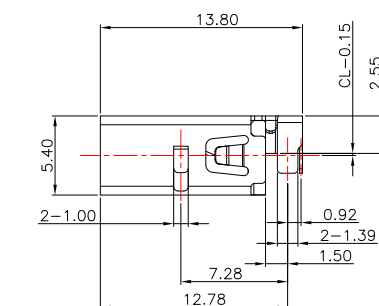
RECOMMENDED PCB LAYOUT



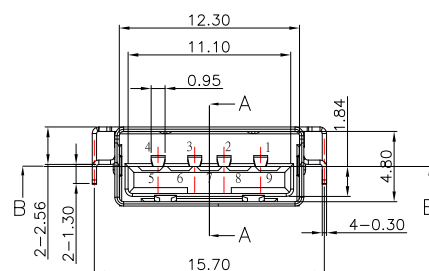
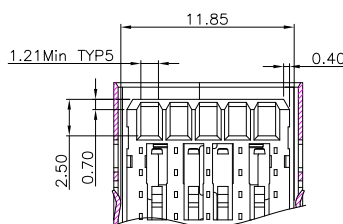
Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST



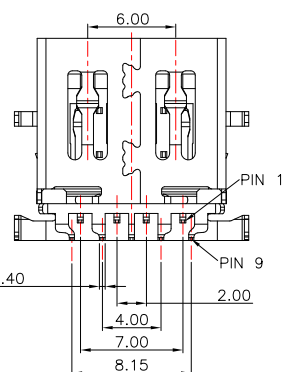
CONNECTOR MATEING



SECTION B-B



(BOTTOM VIEW)



東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 08/19/20
DATE: 08/19/20
DATE: 08/19/20

MAT'L
FINISH
SCALE
SHEET NO.

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
USB A/F 3.0 DIP 沉板, 板上H:2.56mm, 無捲邊反向
SUA-110E5-30xx-S277
SUA-110E5-30xx-S277

SIZE
A4
VER
R4

ITEM NO	DESCRIPTION	DRAWN	DATE
4	新增尺寸標註	Jack	081920
3	新增PCB LAYOUT尺寸標註	Lan	041819
2	新增顏色及材質選項	Jack	042817
1	更新PCB LAYOUT尺寸	Jack	012017